



Vishay General Semiconductor

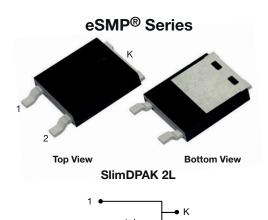
AUTOMOTIVE

RoHS

COMPLIANT

HALOGEN FREE

Surface-Mount ESD Capability Rectifier



LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS					
I _{F(AV)}	8 A				
V _{RRM}	400 V, 600 V				
I _{FSM}	110 A				
V_F at $I_F = 8 A (T_J = 125 °C)$	0.92 V				
T _J max.	175 °C				
Package	SlimDPAK 2L				
Circuit configurations	Single				

FEATURES

- Creepage distance 2.8 mm typical, and clearance distance 3.6 mm typical
- Very low profile typical height of 1.3 mm
- · Ideal for automated placement
- Oxide planar chip junction
- Low forward voltage drop
- · ESD capability
- AEC-Q101 qualified
 - Automotive ordering code: base P/NHM3
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

General purpose, power line polarity protection, in both industry and automotive on board charger (OBC) applications.

MECHANICAL DATA

Case: SlimDPAK 2L

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

Polarity: as marked

MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	SE80PWTG	SE80PWTJ	UNIT			
Device marking code		SE80PWTG	SE80PWTJ				
Maximum repetitive peak reverse voltage	V_{RRM}	400	600	V			
Maximum average forward restified average (Fig. 1)	I _{F(AV)} (1)	8.0					
Maximum average forward rectified current (Fig. 1)	I _{F(AV)} (2)	2.6		A			
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	110		А			
Operating junction and storage temperature range	Ti, Teta	-55 to +175		°C			

Notes

- (1) With infinite heatsink
- (2) Free air, mounted on recommended copper pad area

SE80PWTG, SE80PWTJ

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ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Maximum Instantaneous forward voltage	$I_F = 4.0 \text{ A}$	T 05 °C		0.93	-	
	I _F = 8.0 A T _J = 25 °C	V _F (1)	1.01	1.12	V	
	$I_F = 4.0 \text{ A}$	T _J = 125 °C	VF (*)	0.82	-	V
	$I_F = 8.0 \text{ A}$			0.92	1.07	
Reverse current	Rated V _R	$T_J = 25 ^{\circ}C$	I _R ⁽²⁾	-	15	- μΑ
	nated V _R	T _J = 125 °C		19	150	
Typical reverse recovery time	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{rr} = 0.25 \text{ A}$		t _{rr}	2400	-	ns
Typical junction capacitance	4.0 V, 1 MHz		C_{J}	58	-	pF

Notes

(1) Pulse test: 300 µs pulse width, 1 % duty cycle

(2) Pulse test: pulse width ≤ 40 ms

THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Tomical the amount manisters as	R ₀ JA (1)(2)	76	95	90 AM		
Typical thermal resistance	R _{0JM} (3)	2.4	3	°C/W		

Notes

 $^{(1)}$ The heat generated must be less than thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$

(2) Thermal resistance junction to ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint

(3) Thermal resistance junction-to-mount to follow JEDEC® 51-14 transient dual interface test method (TDIM)

IMMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS ($T_A = 25~^{\circ}\text{C}$ unless otherwise noted)					
STANDARD	TEST TYPE	TEST CONDITIONS	SYMBOL	CLASS	VALUE
AEC-Q101-001	Human body model (contact mode)	$C = 100 \text{ pF}, R = 1.5 \text{ k}\Omega$	V _C	НЗВ	> 8 kV

ORDERING INFORMATION (Example)							
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE BASE QUANTITY DELIVERY MODE					
SE80PWTJ-M3/I	0.184	I	4500	13" diameter plastic tape and reel			
SE80PWTJHM3/I (1)	0.184	I	4500	13" diameter plastic tape and reel			

Note

(1) AEC-Q101 qualified

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RATINGS AND CHARACTERISTICS CURVES (T_A = 25 °C unless otherwise noted)

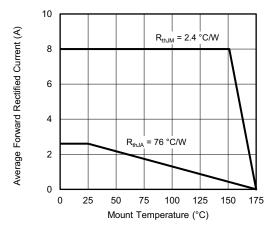


Fig. 1 - Maximum Forward Current Derating Curve

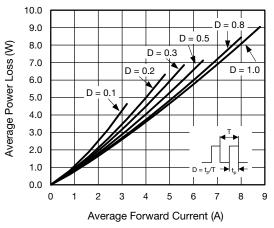


Fig. 2 - Forward Power Loss Characteristics

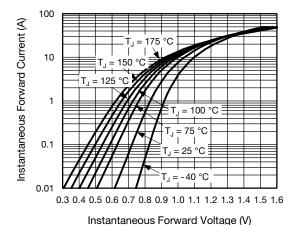


Fig. 3 - Typical Instantaneous Forward Characteristics

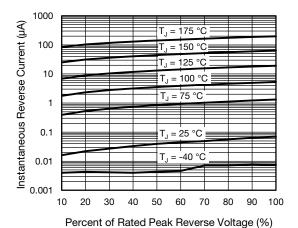


Fig. 4 - Typical Reverse Leakage Characteristics

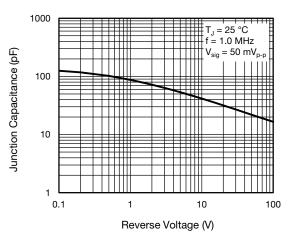


Fig. 5 - Typical Junction Capacitance

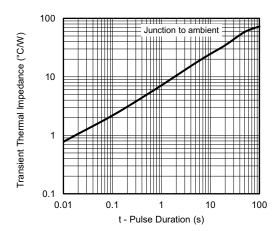


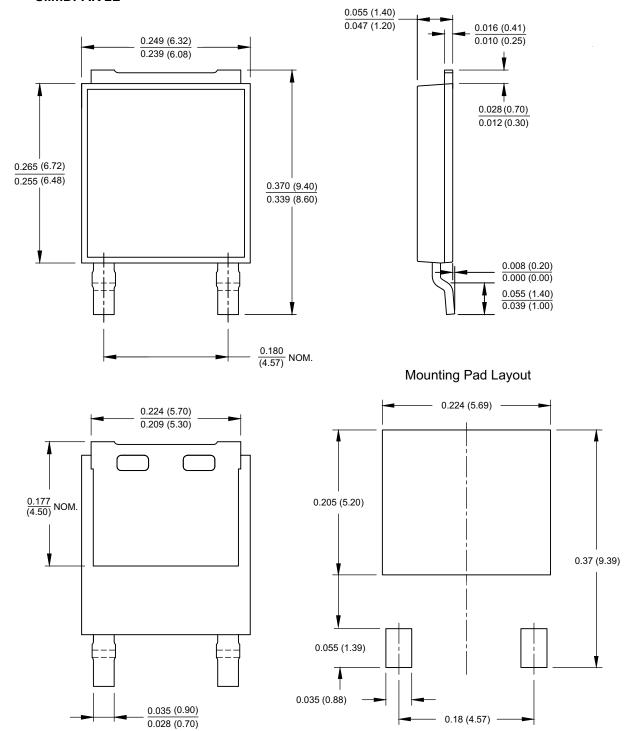
Fig. 6 - Typical Transient Thermal Impedance



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PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SlimDPAK 2L



Note

· The suggested mounting pad layout is provided for reference only, as actual pad layouts may vary depending on application



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